

DESCRIPTION

The SPN1026 is the Dual N-Channel enhancement mode field effect transistors are produced using high cell density DMOS technology. These products have been designed to minimize on-state resistance while provide rugged, reliable, and fast switching performance. They can be used in most applications requiring up to 320mA DC and can deliver pulsed currents up to 1.0A. These products are particularly suited for low voltage, low current applications such as small servo motor control, power MOSFET gate drivers, and other switching applications.

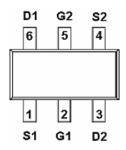
APPLICATIONS

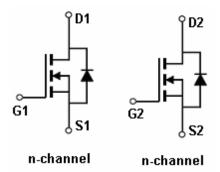
- Drivers: Relays, Solenoids, Lamps, Hammers, Display, Memories, Transistors, etc.
- High saturation current capability. Direct Logic-Level Interface: TTL/CMOS
- Battery Operated Systems
- Solid-State Relays

FEATURES

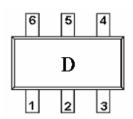
- \bullet 60V/0.50A, RDS(ON)= 4.0 Ω @VGS=10V
- 60V/0.30A, RDS(ON)= 5.0Ω @VGS=5V
- ◆ Super high density cell design for extremely low RDS (ON)
- Exceptional on-resistance and maximum DC current capability
- ◆ SOT-563 / SC-89-6L package design

PIN CONFIGURATION(SOT-563/SC-89-6L)





PART MARKING



PIN DESCRIPTION

Pin	Symbol	Description
1	S1	Source 1
2	G1	Gate 1
3	D2	Drain 2
4	S2	Source 2
5	G2	Gate 2
6	D1	Drain1

ORDERING INFORMATION

Part Number	Package	Part Marking
SPN1026S56RG	SOT-563	D

% Week Code : $A \sim Z(1 \sim 26)$; $a \sim z(27 \sim 52)$

※ SPN1026S56RG : Tape Reel ; Pb − Free

ABSOULTE MAXIMUM RATINGS (TA=25°C Unless otherwise noted)

Parameter	Symbol	Typical	Unit	
Drain-Source Voltage		Vdss	60	V
Gate –Source Voltage - Continuous		VGSS	±20	V
Gate –Source Voltage - Non Repetitive (t _p < 50μs)		VGSS	±40	V
Continuous Drain Current(Tj=150°C)	TA=25°C	ID	0.32	A
Pulsed Drain Current (*)	Ірм	1.0	A	
Continuous Source Current(Diode Conduction)		Is	0.25	A
Power Dissipation	TA=25°C	PD	0.30	W
Operating Junction Temperature		Тл	- 55 ∼ 150	$^{\circ}\!\mathbb{C}$
Storage Temperature Range		Tstg	- 55 ∼ 150	$^{\circ}\! \mathbb{C}$
Thermal Resistance-Junction to Ambient		RθJA	375	°C/W

(*) Pulse width limited by safe operating area

ELECTRICAL CHARACTERISTICS (TA=25°C Unless otherwise noted)

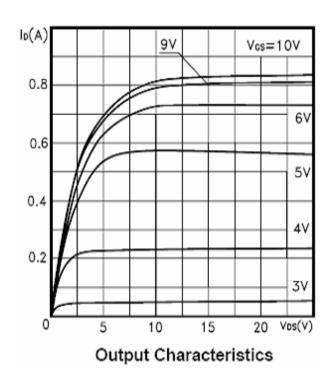
Parameter	Symbol	Conditions	Min.	Тур	Max.	Unit	
Static	<u> </u>						
Drain-Source Breakdown Voltage	V(BR)DSS	V _{GS} =0V,I _D =250uA	60			V	
Gate Threshold Voltage	VGS(th)	VDS=VGS,ID=250uA	1.0	1.7	2.5	7 V	
Gate Leakage Current	Igss	VDS=0V,VGS=±20V			±100	nA	
		V _{DS} =50V,V _{GS} =0V			10	nA	
Zero Gate Voltage Drain Current	IDSS	V _{DS} =50V,V _{GS} =0V T _J = 85°C			100		
Drain-Source On-Resistance	RDS(on)	Vgs=10V,Id=0.50A		2.8	4.0	Ω	
	` ′	V _{GS} = 5V,I _D =0.30A		3.5	5.0		
Source-drain Current	ISD				0.32	A	
Source-drain Current (pulsed)	IsDM (2)				1.4	A	
Forward Transconductance	Gfs(1)	$V_{DS} = 10 \text{ V}, I_{D} = 0.5 \text{ A}$		0.6		S	
Diode Forward Voltage	VsD(1)	$V_{GS} = 0 \text{ V}, I_{S} = 0.2 \text{A}$		0.85	1.5	V	
Dynamic							
Total Gate Charge	Qg			1.4	2.0	nC	
Gate-Source Charge	Qgs	$V_{DD} = 30 \text{ V}, I_{D} = 1 \text{ A}, V_{GS} = 5 \text{ V}$		0.8			
Gate-Drain Charge	Qgd	- V G 5 V		0.5		1	
Input Capacitance	Ciss			43			
Output Capacitance	Coss	$V_{DS} = 25 \text{ V, } f = 1 \text{ MHz,}$ $V_{GS} = 0$		20		pF	
Reverse Transfer Capacitance	Crss	V GS — 0		6		1	
	td(on)			5		ns	
Turn-On Time	tr	$V_{DD} = 30 \text{ V}, I_{D} = 0.5 \text{ A}$		15			
T. OMT.	td(off)	$R_G = 4.7\Omega \text{ VGs} = 4.5 \text{ V}$		7			
Turn-Off Time	tf]		8			

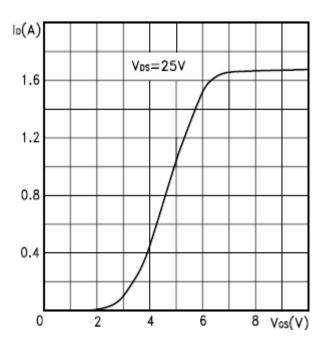
⁽¹⁾ Pulsed: Pulse duration = 300 μ s, duty cycle 1.5 %.

⁽²⁾ Pulse width limited by safe operating area.

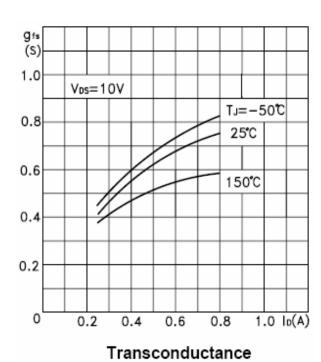


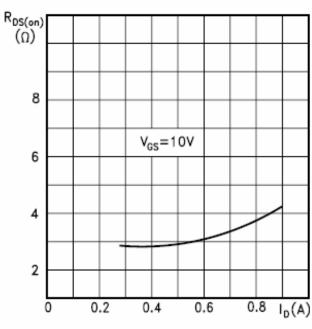
TYPICAL CHARACTERISTICS







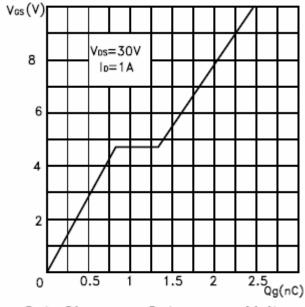




Static Drain-source On Resistance



TYPICAL CHARACTERISTICS



f=1MHz V_{GS}=0V

80

Crss

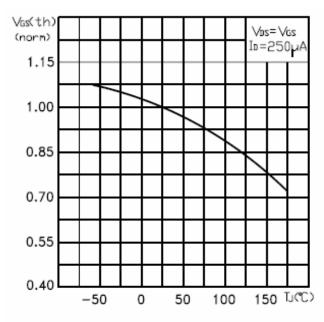
Crss

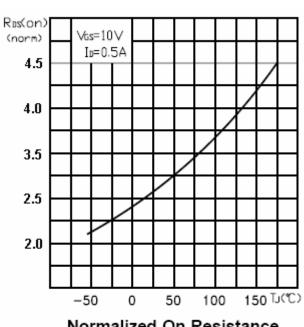
Coss

0 10 20 30 40 V_{OS}(V)

Gate Charge vs Gate-source Voltage

Capacitance Variations



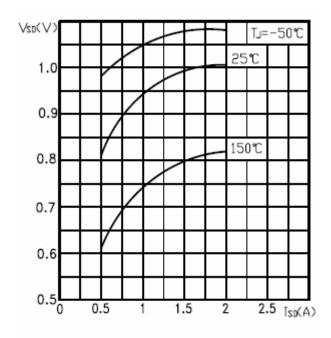


Normalized Gate Threshold Voltage vs Temperature

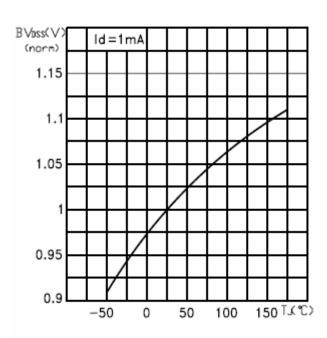
Normalized On Resistance vs Temperature



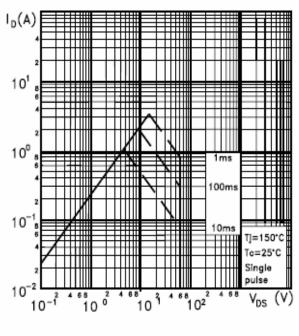
TYPICAL CHARACTERISTICS



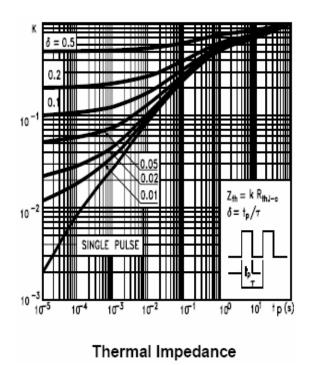
Source-Drain Forward



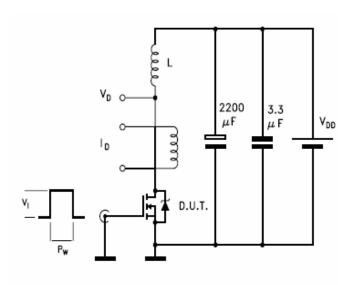
Normalized BVDSS vs Temperature



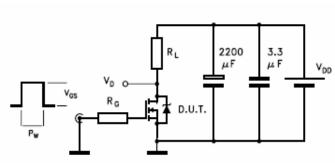
Safe Operating Area



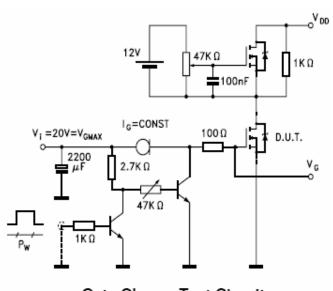
TYPICAL TESTING CIRCUIT



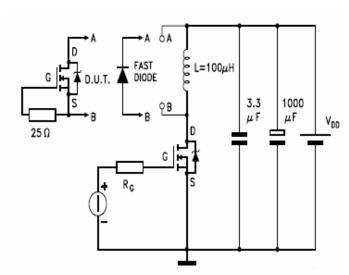
Unclamped Inductive Load Test



Switching Times Test Circuit



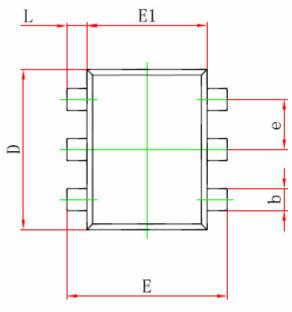
Gate Charge Test Circuit

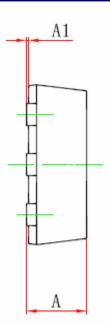


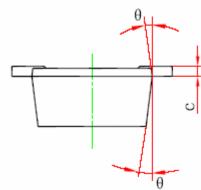
Test Circuit For Inductive Load Switching and Diode Recovery Times



SOT-563 PACKAGE OUTLINE







Symbol	Dimensions in Millimeters		Dimensions in Inches		
	Min.	Max,	MIn.	Max,	
A	0. 525	0.600	0.021	0.024	
A1	0.000	0.050	0.000	0.002	
e	0.450	0.550	0.018	0.022	
С	0.090	0.160	0.004	0.006	
D	1. 500	1.700	0.059	0.067	
b	0.170	0.270	0.007	0.011	
E1	1.100	1.300	0.043	0.051	
Е	1. 500	1.700	0.059	0.067	
L	0.100	0.300	0.004	0.012	
6	7 °REF.		7 °REF.		

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SYNC Power Corporation
9F-5, No.3-2, Park Street
NanKang District (NKSP), Taiwan, 115, R.O.C
Phone: 886-2-2655-8178

Fax: 886-2-2655-8468 ©http://www.syncpower.com